Set Name side by side	Query	Hit Count	Set Name result set
DB=USPT; PLUR=YES; OP=ADJ			
L17	wafer bonding near2 method.ti. and etched	2	L17
L16	wafer bonding near2 method.ti. and etched.ti.	0	L16
L15	wafer bonding near2 method.ti. and filled	3	L15
L14	wafer bonding.ti. and etched and filled	3	L14
L13	wafer bonding.ti. and etched near10 filled	0	L13
L12	wafer fusion.ti.	4	L12
L11	wafer fusion.ab.	15	L11
L10	wafer bonding near2 method.ti.	7	L10
DB=JPAB,EPAB,DWPI; PLUR=YES; OP=ADJ			
L9	wafer bonding near2 method.ti.	38	L9
L8	L7 and (holes or pockets or vias)	9	L8
L7	wafer bonding.ti. or wafer fusion.ti.	229	L7
DB=USPT; PLUR=YES; OP=ADJ			
L6	(l2 or l3) and (holes or pockets)	69	L6
L5	(l2 or l3) and holes or pockets	100362	L5
L4	(l2 or l3) and patterned.ab.	4	L4
L3	(wafer bonding or wafer fusion).ab.	114	L3
L2	hybrid wafer.ab. or hybrid substrate.ab.	37	L2
L1	hybrid wafers	72	L1

END OF SEARCH HISTORY